**PATENT** 

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wen-Chou Vincent Wang, et al.

Attorney Docket No.: ALTRP100/A1198

Application No.: 10/719,218

Examiner: Shrinivas H. Rao

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL AND DESIGN

FOR ASSEMBLING A LOW-K SI DIE TO ACHIEVE AN INDUSTRIAL GRADE

RELIABILITY WIRE BONDING PACKAGE

CERTIFICATE OF TRANSMISSION

I hereby certify that this correspondence is being transmitted via facsimile to the U.S. Papent Shrinivas H. Rao at facsimile telephone number (571) 273-8300 on June 1, 2006.

Printed Name: Leslie Russell

## <u>AMENDMENT B</u>

(Submitted with an RCE herewith)

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Responsive to the Final Office Action mailed 8 March 2006 and the Advisory Action mailed 17 May 2006, the period of response which extends to June 8, 2006, please consider the following remarks and amend the above identified Application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 5 of this paper.

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